Product Preview

SWITCHMODE Power Rectifier 60 V, 20 A

Features and Benefits

- Low Power Loss/High Efficiency
- High Surge Capacity
- 20 A Total (10 A Per Diode Leg)
- Guard-Ring for Stress Protection
- This is a Pb-Free Device

Applications

- Power Supply Output Rectification
- Power Management
- Instrumentation

Mechanical Characteristics:

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 1.9 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 50 Units Per Plastic Tube

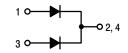
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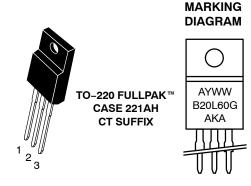


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SCHOTTKY BARRIER RECTIFIER 20 AMPERES 60 VOLTS





A = Assembly Location

= Year

WW = Work Week
B20L60 = Device Code
G = Pb-Free Package
AKA = Polarity Designator

ORDERING INFORMATION

Device	Package	Shipping
MBRJ20L60CTG	TO-220AH (Pb-Free)	50 Units / Rail

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS (Per Diode Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	60	V
	I _{F(AV)}	10 20	А
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	240	А
Operating Junction Temperature (Note 1)	TJ	-55 to +150	°C
Storage Temperature	T _{stg}	-65 to +175	°C
ESD Ratings: Machine Model = C Human Body Model = 3B		> 400 > 8000	V

THERMAL CHARACTERISTICS

ſ	Maximum Thermal Resistance			°C/W
	- Junction-to-Case	$R_{\theta JC}$	3.9	
	Junction-to-Ambient	$R_{ hetaJA}$	105	

ELECTRICAL CHARACTERISTICS (Per Diode Leg)

Rating	Symbol	Тур	Max	Unit
Maximum Instantaneous Forward Voltage (Note 2) $ \begin{aligned} &(I_F=10~A,T_C=25^\circ\text{C})\\ &(I_F=10~A,T_C=125^\circ\text{C})\\ &(I_F=20~A,T_C=25^\circ\text{C})\\ &(I_F=20~A,T_C=125^\circ\text{C}) \end{aligned} $	V _F	0.53 0.49 0.68 0.64	0.57 0.54 0.73 0.69	V
Maximum Instantaneous Reverse Current (Note 2) (Rated DC Voltage, $T_C = 25^{\circ}C$) (Rated DC Voltage, $T_C = 125^{\circ}C$)	İR	118 52	380 96	μA mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.
- 2. Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

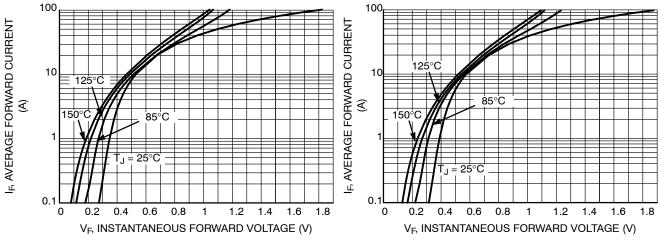


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage

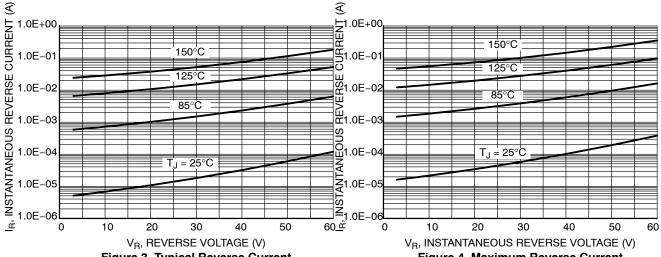


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

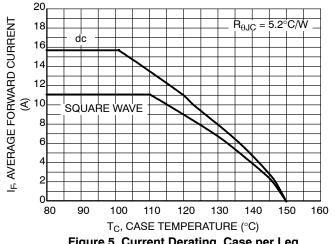


Figure 5. Current Derating, Case per Leg

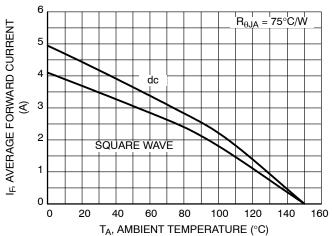


Figure 6. Current Derating, Ambient per Leg

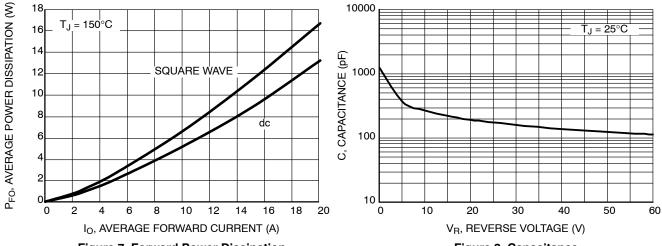


Figure 7. Forward Power Dissipation

Figure 8. Capacitance

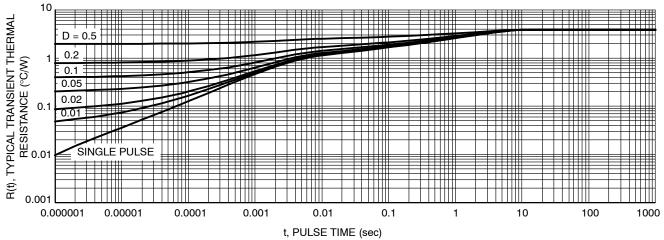
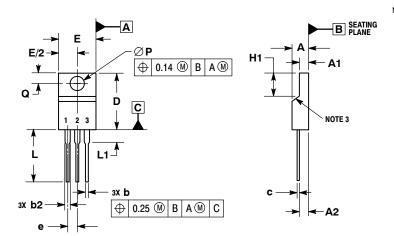


Figure 9. Typical Transient Thermal Response, Junction-to-Case

PACKAGE DIMENSIONS

TO-220 FULLPACK, 3-LEAD CASE 221AH ISSUE C



NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.

- 3. CONTOUR UNCONTROLLED IN THIS AREA.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH AND GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE TO BE MEASURED AT OUTERMOST EXTREME OF THE PLASTIC BODY.
 DIMENSION b2 DOES NOT INCLUDE DAMBAR
- PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 2.00.

	MILLIMETERS		
DIM	MIN	MAX	
Α	4.30	4.70	
A1	2.50	2.90	
A2	2.50	2.70	
b	0.54	0.84	
b2	1.10	1.40	
С	0.49	0.79	
D	14.70	15.30	
Е	9.70	10.30	
е	2.54 BSC		
H1	6.70	7.10	
L	12.70	14.73	
L1		2.80	
P	3.00	3.40	
Q	2.80	3.20	

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